DB3J313K

Silicon epitaxial planar type

For small current rectification DB3X313K in SMini3 type package

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

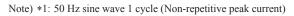
■ Marking Symbol: 4J

■ Packaging

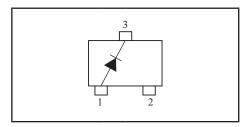
 $DB3J313K0L \quad Embossed \ type \ (Thermo-compression \ sealing): \ 3\,000 \ pcs \ / \ reel \ (standard)$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	30	V	
Maximum peak reverse voltage	V _{RM}	30	V	
Forward current (Average)	I _{F(AV)}	200	mA	
Peak forward current	I_{FM}	300	mA	
Non-repetitive peak forward surge current *1	I _{FSM}	1	A	
Junction temperature	T _j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Unit: mm 2. 0 0. 3 0. 13 (0. 65)(0. 65) 1. 3 1: Anode 2: N.C. 3: Cathode Panasonic SMini3-F2-B JEITA SC-85 Code —

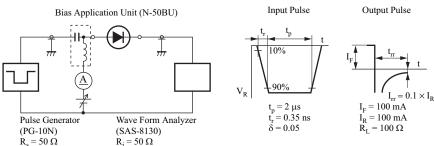


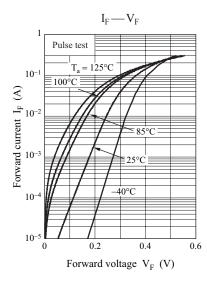
■ Electrical Characteristics $T_a = 25$ °C±3°C

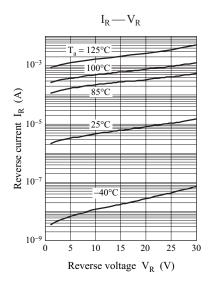
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μΑ
Terminal capacitance	Ct	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R,$ $R_L = 100 \Omega$		1.5		ns

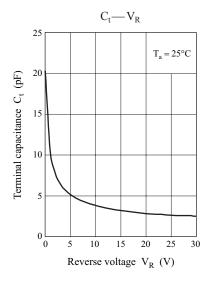
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 1 GHz
 - *1: t_{rr} measurement circuit





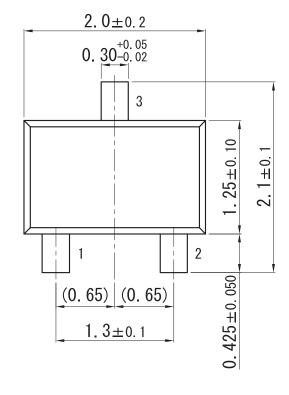


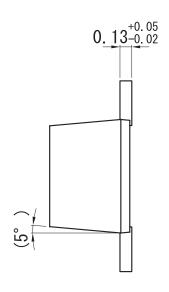


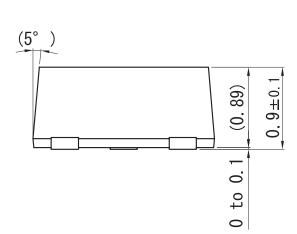
Ver. DED 2

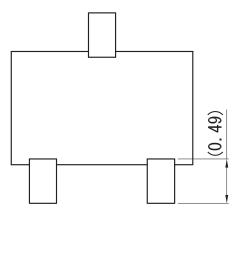
SMini3-F2-B

Unit: mm

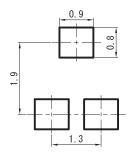








■ Land Pattern (Reference) (Unit: mm)



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